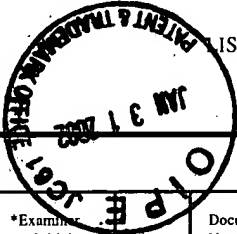


Form PTO-1449

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

ATTY. DOCKET NO.
M122-1741

SERIAL NO.
09/875,501



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APPLICANT
Klaus Florian Schuegraf et al.

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U.S. PATENT DOCUMENTS

| *Examiner Initial | Document Number | Date | Name | Class | Subclass | Filing Date If Appropriate |
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| EO | AA 5,439,833 | 08/1995 | Herbert, et al. | 437 | 31 | |
| | AB | | | | | |
| | AC | | | | | |
| | AD | | | | | |
| | AE | | | | | |
| | AF | | | | | |
| | AG | | | | | |
| | AH | | | | | |
| | AI | | | | | |
| | AJ | | | | | |
| | AK | | | | | |

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| Document Number | Date | Country | Class | Subclass | Translation | |
|-----------------|---------|----------------|-------|----------|-------------|----|
| | | | | | Yes | No |
| AL 401276761-A | 11/1989 | Japan - Nonaka | | | | |

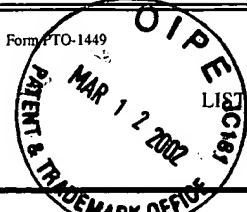
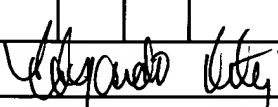
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

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| EO | AM | Ku et al. "The application of ion-beam mixing, coped silicide, a rapid thermal processing self-aligned silicide technology" VLSI Technology, Systems and Applications, May 17-19, 1989, Pages 337-341 |
| EO | AN | Lange, H.; "Physical Properties of Semiconducting Transition Metal Silicides and their Prospects in Si-Based Device Applications"; IEEE 1998; Pages 247-250. |
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4/3/02

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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|---|----|--|---------|---|-------|--------------------------|----------------------------|
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| | | | | FILING DATE June 4, 2001 | | GROUP 2815 | |
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| EO | AA | 4,354,309 | 10/1982 | Gardiner et al. | | | |
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| | | | | | | | Yes No |
| EO | | JP 02265248 A | 04/1989 | Japan - Kuriyama, Hiroko | | | |
| OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.) | | | | | | | |
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| | AO | | | | | | |
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| <div style="display: flex; align-items: center; justify-content: center;"> <div style="border: 2px solid black; border-radius: 50%; padding: 10px; text-align: center; margin-right: 10px;"> OIPE MAR 12 2002 PATENT & TRADEMARK OFFICE </div> <div> STATE OF ART CITED BY APPLICANT (Use several sheets if necessary) </div> </div> | | | | | APPLICANT Klaus Florian Schuegraf et al. | | | |
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| EO | AA | 5,350,698 | 09/1994 | Huang et al. | 437 | 26 | <div style="writing-mode: vertical-rl; transform: rotate(180deg);"> RECEIVED MAR 21 2002 TECHNOLOGY CENTER 2800 </div> |
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| | AI | | | | | | |
| | AJ | | | | | | |
| | AK | | | | | | |

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| | | Document Number | Date | Country | Class | Subclass | Translation | |
| | | | | | | | Yes | No |
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| OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.) | | | |
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